


① Substrate: 1.59mm \pm 0.18mm [0.0625" \pm 0.007"]
FR4/G10 or equivalent high temp material.

② Pins: material- Brass Alloy 360 1/2 hard; finish-
0.25 μ m [10 μ] Au over 1.27 μ m [50 μ] Ni (min.).

Description: Giga-snaP BGA SMT Land Socket

324 position BGA surface mount land pattern to terminal pins (1.0mm [0.039"] centers, 16x16 array)

Tolerances: diameters \pm 0.03mm [\pm 0.001"], PCB perimeters \pm 0.13mm [\pm 0.005"], PCB thicknesses \pm 0.18mm [\pm 0.007"], pitches (from true position) \pm 0.08mm [\pm 0.003"], all other tolerances \pm 0.13mm [\pm 0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

	LS-BGA324G-41 Drawing © 2004 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com	Status: Released	Scale: 5:1	Rev: C
		Drawing: H. Hansen		Date: 7/27/04
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